

Title (en)

FRICION MATERIAL PRODUCTION DEVICE AND FRICTION MATERIAL PRODUCTION METHOD

Title (de)

VORRICHTUNG UND VERFAHREN ZUR HERSTELLUNG VON REIBUNGSMATERIAL

Title (fr)

DISPOSITIF DE PRODUCTION DE MATÉRIAU DE FRICTION ET PROCÉDÉ DE PRODUCTION DE MATÉRIAU DE FRICTION

Publication

EP 3838443 A4 20220518 (EN)

Application

EP 19850707 A 20190813

Priority

- JP 2018152363 A 20180813
- JP 2019031836 W 20190813
- JP 2019132171 A 20190717

Abstract (en)

[origin: EP3838443A1] The problem to be solved by the present invention is to enable a friction material to be efficiently produced. The present invention is a friction material production device for sintering a friction material. The device is provided with: a jig for holding a workpiece laminate, that is, a preform of the friction material, in a lamination direction; a conveyance mechanism forming a conveyance path of the jig; and heating devices disposed at some point on the conveyance path and used for heating the laminate held by the jig by means of an infrared ray from the side with respect to the lamination direction.

IPC 8 full level

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CPC (source: EP)

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C-Set (source: EP)

1. **B22F 2999/00** + **B22F 3/003** + **B22F 3/02** + **B22F 3/10** + **B22F 2201/10**
2. **B22F 2998/10** + **B22F 3/02** + **B22F 7/062** + **B22F 3/10**

Citation (search report)

- [Y] US 2017182683 A1 20170629 - GOLDBACH KAI [DE], et al
- [Y] JP S5265703 A 19770531 - MITSUBISHI METAL CORP
- [YD] CN 205437147 U 20160810 - QIN WENLONG
- [Y] JP 2016141847 A 20160808 - SUMITOMO DENKO SHOKETSU GOKIN KK
- See references of WO 2020036176A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

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